October 24, 2017

09:00  Welcome
09:10  Overview “LOMID”
      U. Vogel (Fraunhofer FEP, Germany)
09:40  Overview “LUMENTILE”
      G. Giuliani (University of Pavia, Italy)
09:50  LUMENTILE – “Hybrid large area systems R2R manufacturing”
      K. Keranen (VTT, Finland)
10:10  LUMENTILE – “Light management solutions for large-area backlighting”
      G. Giuliani (University of Pavia, Italy)
10:30  Coffee
11:00  Overview “ROLL-OUT”
      A. Alastalo (VTT, Finland)
11:20  ROLL-OUT – “Thin film sensors and integration for automotive and packaging solutions”
      M. Jank (Fraunhofer IISB, Germany)
11:40  Overview “LORIX”
      A. Martinent-Beaumont (CEA, France)
12:00  LORIX – “Challenges for industrializing OTFT for TOLAE applications”
      G. Trovarelli (Plastic Logic GmbH, Germany)
12:20  Lunch
13:20  Overview “TransFlexTeg”
      I. Ferreira (University Lisboa, Portugal)
13:30  TransFlexTeg – “Large-area distributed thermocouple concept for thermal distribution mapping”
      Taneli Juntunen (Aalto University, Finland)
13:50  TransFlexTeg – “Wireless sensor system based on transparent and flexible TEGs”
      K. Jaakkola (VTT, Finland)
14:10  Coffee
14:30  Overview “ALABO”
      U. Klotzbach (Fraunhofer IWS, Germany)
14:40  ALABO – “Process Innovation and Impact”
      M. Anderson (Heliatek, Germany)
15:00  ALABO – “Scribing organic Photovoltaic on thin film barrier with laser sources”
      T. Kuntze (Fraunhofer IWS, Germany)
15:20  Poster Session
16:30  Lab Tour Fraunhofer IWS & FEP
18:30  Dinner (requested: Watzke Brauereiausschank am Goldenen Reiter, Hauptstraße 1, 01067 Dresden)

October 25, 2017

09:00  Welcome
09:05  Overview “OptIntegral”
      E. Piqueras (EURECAT, Spain)
09:25  OptIntegral – “R2R hybrid integration process”
      J. Eveliina (VTT, Finland)
09:45  OptIntegral – “Industrial integration of printed electronics (via injection molding)”
      E. Escudero (EURECAT, Spain)
10:05  HAPPINESS – “Haptic components printed on plastic foil for Automotive applications”
      A. Latour (CEA Grenoble, France)
10:35  SmartEEs – “A Sustainable Marketplace for the Adoption, Ramp-up and Transfer of Emerging Electronic Solutions”
      C. May (Fraunhofer FEP, Germany)
11:05  Overview “PiScale”
      C. Keibler (Fraunhofer FEP, Germany)
11:35  Panel discussion and summary
      Real-life testing / validation for applicability to industrial and societal challenges
12:30  Lunch
Advanced Thin, Organic and Large Area Electronics (TOLAE) technologies is an emerging technology and forms the basis for advanced products in large area electronics. TOLAE offers a platform for creating advanced technology and products that could penetrate a multitude of markets, including light weight, flexible and/or stretchable. TOLAE suits large market sectors such as the textile, automotive, health, paper, plastic, advertising or construction industries. Horizon 2020 is investing heavily in the translation of thin, organic and large-area electronics from the lab to the market. Every TOLAE project benefits from a consortium consisting of academic and industrial partners, often representing the entire value chain. The involvement of multiple stakeholders – from Research and Development to SME, large companies and Leading Network for the Next Generation of Thin, Organic as well as Large Area Electronics are poised to push up and commercialize results.

We will give you an overview about the latest results on European funded projects.

**PROJECTS**

- **ALABO | HAPPINESS | LOMID | LORIX**
- **LUMENTILE | OptIntegral | PiScale | ROLL-OUT | TransFlexTeg | SmartEEs**

**INVITATION**

**Location:**
Fraunhofer-Institut für Werkstoff- und Strahltechnik
Winterbergstraße 28
01277 Dresden, Germany
www.iws.fraunhofer.de/en

**Workshop language:**
English

**Workshop fee:**
280 €
90 € for project member
230 € for members of OE-A, OES and AFELIM (payable on receipt of the invoice)

**Registration deadline:**
October 10, 2017

Cancellation of registration is possible by October 17, 2017. Afterwards full costs will be charged.

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**ORGANIZATION**

Advanced Laser Ablation on Barrier films for Organic and large area electronic devices (ALABO)

Haptic Printed and Patterned Interfaces for Sensitive Surface (HAPPINESS)

Large cost-effective OLED microdisplays and their applications (LOMID)

Large Organic Robust Imager for X-Ray Sensing (LORIX)

LUMinous ElectroNical TILE (LUMENTILE)

Advertisement displays manufactured by hybrid in-mould integration (OptIntegral)

Bringing flexible organic electronics to pilot innovation scale (PiScale)

High-performance, Flexible, AUTOnomous Systems manufactured with Unique, Industrial ROLL-to-roll equipments (ROLL-OUT)

Large area transparent thin film thermoelectric devices for smart window and flexible applications (TransFlexTeg)

SMART Emerging Electronics Servicing DIH (SmartEEs)